## 4V to 42V, 25mA, Ultra-Small, High-Efficiency, Synchronous Step-Down DC-DC Converter with $22 \mu \mathrm{~A}$ No-Load Supply Current

## General Description

The MAX17530 high-efficiency, high-voltage, synchronous step-down DC-DC converter with integrated MOSFETs operates over a 4 V to 42 V input. The converter can deliver up to 25 mA and generates output voltages from 0.8 V up to $0.9 \times \mathrm{V}_{\mathrm{IN}}$. The feedback (FB) voltage is accurate to within $\pm 1.75 \%$ over $-40^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$.
The MAX17530 uses peak-current-mode control. The device can be operated in pulse-width modulation (PWM) or pulse-frequency modulation (PFM) modes.
The device is available in a $10-\mathrm{pin}(3 \mathrm{~mm} \times 2 \mathrm{~mm})$ TDFN and $10-$ pin $(3 \mathrm{~mm} \times 3 \mathrm{~mm}) \mu \mathrm{MAX}{ }^{\circledR}$ packages. Simulation models are available.

## Applications

- Industrial Sensors and Process Control
- High-Voltage LDO Replacement
- Battery-Powered Equipment
- HVAC and Building Control


## Ordering Information appears at end of data sheet.

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## Benefits and Features

- Reduces External Components and Total Cost
- No Schottky-Synchronous
- Internal Compensation for Any Output Voltage
- Built-In Soft-Start
- All-Ceramic Capacitors, Compact Layout
- Reduces Number of DC-DC Regulators to Stock
- Wide 4 V to 42 V Input
- Adjustable 0.8V Up to $0.9 \times \mathrm{V}_{\mathrm{IN}}$ Output
- 100 kHz to 2.2 MHz Adjustable Switching Frequency with External Synchronization
- Reduces Power Dissipation
- $22 \mu \mathrm{~A}$ Quiescent Current
- Peak Efficiency > 90\%
- PFM Enables Enhanced Light-Load Efficiency
- 1.2 $\mu \mathrm{A}$ Shutdown Current
- Operates Reliably in Adverse Environments
- Peak Current-Limit Protection
- Built-In Output-Voltage Monitoring RESET
- Programmable EN/UVLO Threshold
- Monotonic Startup into Prebiased Load
- Overtemperature Protection
- High Industrial $-40^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$ Ambient Operating Temperature Range $/-40^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$ Junction Temperature Range


## Typical Application Circuits-High-Efficiency 5V, 25mA Regulator



# 4V to 42V, 25mA, Ultra-Small, High-Efficiency Synchronous Step-Down DC-DC Converter with $22 \mu \mathrm{~A}$ No-Load Supply Current 

| solute Maximum Ratings |
| :---: |
| , |
| X to GND...............................................-0.3V to IN + 0.3V |
| RT/SYNC, SS, FB, MODE to GND ........................-0.3V to 6V |
| LX Total RMS Current ................................................. $\pm 0.8 \mathrm{~A}$ |
| Output Short-Circuit Duration |
| Continuous Power Dissipation ( $\mathrm{T}_{\mathrm{A}}=+70^{\circ} \mathrm{C}$ ) |
| TDFN (derate $14.9 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ above $+70^{\circ} \mathrm{C}$ ) ............. 1188 |
| $\mu \mathrm{MAX}$ (derate $8.8 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ above $+70^{\circ} \mathrm{C}$ ) ................ 707.3 mW |

Operating Temperature Range (Note 1)........... $-40^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$
Junction Temperature ..................................................... $+150^{\circ} \mathrm{C}$
Storage Temperature Range ............................ $65^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$
Lead Temperature (soldering, 10s) ................................. $+300^{\circ} \mathrm{C}$
Soldering Temperature (reflow)....................................... $+260^{\circ} \mathrm{C}$

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note 1: Junction temperature greater than $+125^{\circ} \mathrm{C}$ degrades operating lifetimes.

## Package Information

| PACKAGE TYPE: 10 TDFN |  |
| :---: | :---: |
| Package Code | T1032N+1 |
| Outline Number | 21-0429 |
| Land Pattern Number | 90-0082 |
| THERMAL RESISTANCE, FOUR-LAYER BOARD |  |
| Junction to Ambient ( ${ }_{\text {JAA }}$ ) | $67.3^{\circ} \mathrm{C} / \mathrm{W}$ |
| Junction to Case ( $\theta_{\mathrm{JC}}$ ) | $18.2^{\circ} \mathrm{C} / \mathrm{W}$ |
|  |  |
| PACKAGE TYPE: $10 \mu$ MAX |  |
| Package Code | U10+5 |
| Outline Number | $\underline{\text { 21-0061 }}$ |
| Land Pattern Number | 90-0330 |
| THERMAL RESISTANCE, FOUR-LAYER BOARD |  |
| Junction to Ambient ( $\theta_{\text {JA }}$ ) | $113.1^{\circ} \mathrm{C} / \mathrm{W}$ |
| Junction to Case ( $\theta_{\mathrm{JC}}$ ) | $42^{\circ} \mathrm{C} / \mathrm{W}$ |

For the latest package outline information and land patterns (footprints), go to www.maximintegrated.com/packages. Note that a " + ", "\#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.maximintegrated.com/thermal-tutorial.

## Electrical Characteristics

$\left(\mathrm{V}_{\mathrm{IN}}=24 \mathrm{~V}, \mathrm{~V}_{\mathrm{GND}}=0 \mathrm{~V}, \mathrm{~V}_{\mathrm{OUT}}=3.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{FB}}=0.85 \mathrm{~V}, \mathrm{~V}_{\mathrm{EN} / \mathrm{UVLO}}=1.5 \mathrm{~V}, \mathrm{RT} / \mathrm{SYNC}=191 \mathrm{k} \Omega, \mathrm{LX}=\mathrm{SS}=\mathrm{MODE}=\overline{\mathrm{RESET}}=\right.$ unconnected; $\mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$, unless otherwise noted. Typical values are at $\mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$. All voltages are referenced to GND , unless otherwise noted.) (Note 2)

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| INPUT SUPPLY (IN) |  |  |  |  |  |  |
| Input Voltage Range | $\mathrm{V}_{\text {IN }}$ |  | 4 |  | 42 | V |
| Input Shutdown Current | $\mathrm{I}_{\text {IN-SH }}$ | $\mathrm{V}_{\text {EN/UVLO }}=0 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$ | 0.67 | 1.2 | 2.25 | $\mu \mathrm{A}$ |
| Input Supply Current | $\mathrm{I}_{\text {Q-PFM }}$ | $\mathrm{V}_{\text {MODE }}=$ unconnected (Note 3) |  | 18 | 32 |  |
|  | $\mathrm{I}_{\mathrm{Q}-\mathrm{PWM}}$ | Normal switching mode, $\mathrm{V}_{\mathrm{IN}}=24 \mathrm{~V}$ | 180 | 485 | 650 |  |
| EXTERNAL BIAS (V ${ }_{\text {OUT }}$ ) |  |  |  |  |  |  |
| $V_{\text {OUT }}$ Switchover Threshold |  |  | 2.96 | 3.05 | 3.12 | V |
| ENABLE/UVLO (EN/UVLO) |  |  |  |  |  |  |
| EN/UVLO Threshold | $\mathrm{V}_{\text {ENR }}$ | $\mathrm{V}_{\text {EN/UVLO }}$ rising | 1.2 | 1.25 | 1.3 | V |
|  | $\mathrm{V}_{\text {ENF }}$ | $\mathrm{V}_{\text {EN/UVLO }}$ falling | 1.1 | 1.15 | 1.2 |  |
|  | $\mathrm{V}_{\text {EN-TRUESD }}$ | $\mathrm{V}_{\text {EN/UVLO }}$ falling, true shutdown |  | 0.7 |  |  |
| EN/UVLO Leakage Current | IEN | $\mathrm{V}_{\text {EN/UVLO }}=1.3 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$ | -100 |  | +100 | nA |
| POWER MOSFETs |  |  |  |  |  |  |
| High-Side pMOS On-Resistance | $\mathrm{R}_{\text {DS-ONH }}$ | $\mathrm{I}_{\mathrm{LX}}=0.1 \mathrm{~A}$ (sourcing) | 3.2 | 5.9 | 11.1 | $\Omega$ |
| Low-Side nMOS On-Resistance | $\mathrm{R}_{\text {DS-ONL }}$ | $\mathrm{I}_{\mathrm{LX}}=0.1 \mathrm{~A}$ (sinking) | 1.6 | 3.0 | 6 | $\Omega$ |
| LX Leakage Current | ILX-LKG | $\begin{aligned} & \mathrm{V}_{\mathrm{EN}}=0 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}, \\ & \mathrm{~V}_{\mathrm{LX}}=\left(\mathrm{V}_{\mathrm{GND}}+1 \mathrm{~V}\right) \text { to }\left(\mathrm{V}_{\mathrm{IN}}-1 \mathrm{~V}\right) \end{aligned}$ | -1 |  | +1 | $\mu \mathrm{A}$ |
| SOFT-START (SS) |  |  |  |  |  |  |
| Soft-Start Time | $\mathrm{t}_{\text {SS }}$ | SS = unconnected | 4.4 | 5.1 | 5.8 | ms |
| SS Charging Current | Iss | $\mathrm{V}_{\mathrm{SS}}=0.4 \mathrm{~V}$ | 4.7 | 5 | 5.3 | $\mu \mathrm{A}$ |
| FEEDBACK (FB) |  |  |  |  |  |  |
| FB Regulation Voltage | $V_{\text {FB-REG }}$ | MODE = GND | 0.786 | 0.8 | 0.814 | V |
|  |  | MODE = unconnected | 0.786 | 0.812 | 0.826 |  |
| FB Input Leakage Current | $\mathrm{I}_{\text {FB }}$ | $\mathrm{V}_{\mathrm{FB}}=1 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$ | -100 |  | +100 | nA |
| CURRENT LIMIT |  |  |  |  |  |  |
| Peak Current-Limit Threshold | IPEAK-LIMIT |  | 66 | 72 | 78 | mA |
| Negative Current-Limit Threshold | ${ }^{\text {I SINK-LIMIT }}$ | $\mathrm{V}_{\text {MODE }}=\mathrm{GND}$ | 24 | 32 | 40 | mA |
|  |  | $\mathrm{V}_{\text {MODE }}=$ unconnected |  | 0.01 |  |  |
| PFM Current Level | IPFM | $\mathrm{V}_{\text {MODE }}=$ unconnected | 17 | 23 | 29 | mA |
| CURRENT LIMIT |  |  |  |  |  |  |
| Switching Frequency | fsw | $\mathrm{R}_{\mathrm{RT}}=422 \mathrm{k} \Omega$ | 90 | 100 | 111 | kHz |
|  |  | $\mathrm{R}_{\mathrm{RT}}=191 \mathrm{k} \Omega$ | 205 | 220 | 235 |  |
|  |  | $\mathrm{R}_{\mathrm{RT}}=130 \mathrm{k} \Omega$ | 295 | 319 | 340 |  |
|  |  | $\mathrm{R}_{\mathrm{RT}}=69.8 \mathrm{k} \Omega$ | 540 | 592 | 638 |  |
|  |  | $\mathrm{R}_{\mathrm{RT}}=45.3 \mathrm{k} \Omega$ | 813 | 900 | 973 |  |
|  |  | $\mathrm{R}_{\mathrm{RT}}=19.1 \mathrm{k} \Omega$ | 1.86 | 2.08 | 2.3 | MHz |

## Electrical Characteristics (continued)

$\left(\mathrm{V}_{\mathrm{IN}}=24 \mathrm{~V}, \mathrm{~V}_{\mathrm{GND}}=0 \mathrm{~V}, \mathrm{~V}_{\mathrm{OUT}}=3.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{FB}}=0.85 \mathrm{~V}, \mathrm{~V}_{\mathrm{EN} / \mathrm{UVLO}}=1.5 \mathrm{~V}, \mathrm{RT} / \mathrm{SYNC}=191 \mathrm{k} \Omega, \mathrm{LX}=\mathrm{SS}=\mathrm{MODE}=\overline{\mathrm{RESET}}=\right.$ unconnected; $\mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$, unless otherwise noted. Typical values are at $\mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$. All voltages are referenced to GND, unless otherwise noted.) (Note 2)

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Switching-Frequency Adjustable Range |  | See the Switching Frequency (RT/SYNC) section for details | 100 |  | 2200 | kHz |
| SYNC Input Frequency |  |  | $1.1 \times \mathrm{f}_{\text {SW }}$ |  | 2200 | kHz |
| SYNC Pulse Minimum Off-Time |  |  | 40 |  |  | ns |
| SYNC Rising Threshold | $V_{\text {SYNC-H }}$ |  | 1 | 1.22 | 1.44 | V |
| Hysteresis | $\mathrm{V}_{\text {SYNC-HYS }}$ |  | 0.115 | 0.18 | 0.265 |  |
| Number of SYNC Pulses to Enable Synchronization |  |  | 1 |  |  | Cycles |
| TIMING |  |  |  |  |  |  |
| Minimum On-Time | ton-min |  | 46 | 82 | 128 | ns |
| Maximum Duty Cycle | $\mathrm{D}_{\text {MAX }}$ | $\begin{aligned} & \mathrm{f}_{S W} \leq 600 \mathrm{kHz}, \\ & \mathrm{~V}_{\mathrm{FB}}=0.98 \times \mathrm{V}_{\mathrm{FB}-\mathrm{REG}} \end{aligned}$ | 90 | 94 | 98 | \% |
|  |  | $\begin{aligned} & \mathrm{f}_{\mathrm{SW}}>600 \mathrm{kHz}, \\ & \mathrm{~V}_{\mathrm{FB}}=0.98 \times \mathrm{V}_{\mathrm{FB}-\mathrm{REG}} \end{aligned}$ | 87 | 92 |  |  |
| Hiccup Timeout |  |  |  | 51 |  | ms |
| RESET |  |  |  |  |  |  |
| FB Threshold for RESET Rising | $\mathrm{V}_{\text {FB-OKR }}$ | $V_{\text {FB }}$ rising | 93 | 95 | 97 | \% |
| FB Threshold for RESET Falling | $\mathrm{V}_{\text {FB-OKF }}$ | $V_{\text {FB }}$ falling | 90 | 92 | 94 | \% |
| $\overline{\text { RESET }}$ Delay after FB Reaches 95\% Regulation |  |  | 2.1 |  |  | ms |
| RESET Output Level Low |  | $1 \bar{I}_{\text {RESET }}=1 \mathrm{~mA}$ | 0.23 |  |  | V |
| RESET Output Leakage Current Output Leakage Current |  | $\mathrm{V}_{\mathrm{FB}}=1.01 \times \mathrm{V}_{\mathrm{FB}-\mathrm{REG}}, \mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$ | 1 |  |  | $\mu \mathrm{A}$ |
| MODE |  |  |  |  |  |  |
| MODE PFM Threshold | $\mathrm{V}_{\text {MODE-PFM }}$ |  | 1 | 1.22 | 1.44 | V |
| MODE Hysteresis | $\mathrm{V}_{\text {MODE-HYS }}$ |  |  | 0.19 |  | V |
| MODE Internal Pullup Resistor | $\mathrm{R}_{\text {MODE }}$ | $\mathrm{V}_{\text {MODE }}=$ unconnected |  | 123 |  | k $\Omega$ |
|  |  | $\mathrm{V}_{\text {MODE }}=\mathrm{GND}$ | 1390 |  |  |  |
| THERMAL SHUTDOWN |  |  |  |  |  |  |
| Thermal-Shutdown Threshold | $\mathrm{V}_{\text {MODE-PFM }}$ | Temperature rising |  | 160 |  | ${ }^{\circ} \mathrm{C}$ |
| Thermal-Shutdown Hysteresis | $\mathrm{V}_{\text {MODE-HYS }}$ |  |  | 20 |  | ${ }^{\circ} \mathrm{C}$ |

Note 2: All electrical specifications are $100 \%$ production tested at $T_{A}=+25^{\circ} \mathrm{C}$. Specifications over the operating temperature range are guaranteed by design and characterization.
Note 3: Actual $I_{Q-P F M}$ in the application circuit is higher due to additional current in the output voltage feedback resistor divider. For example, $\mathrm{I}_{\mathrm{Q}-\mathrm{PFM}}(\mathrm{MODE}=$ unconnected $)=26 \mu \mathrm{~A}$ for Figure 6, $22 \mu \mathrm{~A}$ for Figure 7, and $78 \mu \mathrm{~A}$ for Figure 11.

## 4V to 42V, 25mA, Ultra-Small, High-Efficiency Synchronous Step-Down DC-DC Converter with $22 \mu \mathrm{~A}$ No-Load Supply Current

## Typical Operating Characteristics

$\left(\mathrm{V}_{\mathrm{IN}}=24 \mathrm{~V}, \mathrm{~V}_{\mathrm{GND}}=0 \mathrm{~V}, \mathrm{~V}_{\mathrm{OUT}}=3.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{EN} / \mathrm{UVLO}}=1.5 \mathrm{~V}, \mathrm{RT} / \mathrm{SYNC}=191 \mathrm{k} \Omega, \mathrm{C}_{\mathrm{IN}}=1 \mu \mathrm{~F}, \mathrm{~T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}\right.$, unless otherwise noted $)$

$\left(\mathrm{V}_{\mathrm{IN}}=24 \mathrm{~V}, \mathrm{~V}_{\mathrm{GND}}=0 \mathrm{~V}, \mathrm{~V}_{\mathrm{OUT}}=3.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{EN} / \mathrm{UVLO}}=1.5 \mathrm{~V}, \mathrm{RT} / \mathrm{SYNC}=191 \mathrm{k} \Omega, \mathrm{C}_{\mathrm{IN}}=1 \mu \mathrm{~F}, \mathrm{~T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}\right.$, unless otherwise noted $)$


Typical Operating Characteristics (continued)
$\left(\mathrm{V}_{\mathrm{IN}}=24 \mathrm{~V}, \mathrm{~V}_{\mathrm{GND}}=0 \mathrm{~V}, \mathrm{~V}_{\mathrm{OUT}}=3.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{EN} / \mathrm{UVLO}}=1.5 \mathrm{~V}, \mathrm{RT} / \mathrm{SYNC}=191 \mathrm{k} \Omega, \mathrm{C}_{\mathrm{IN}}=1 \mu \mathrm{~F}, \mathrm{~T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}\right.$, unless otherwise noted $)$


## 4V to 42V, 25mA, Ultra-Small, High-Efficiency Synchronous Step-Down DC-DC Converter with $22 \mu \mathrm{~A}$ No-Load Supply Current

Typical Operating Characteristics (continued)
$\left(\mathrm{V}_{\mathrm{IN}}=24 \mathrm{~V}, \mathrm{~V}_{\mathrm{GND}}=0 \mathrm{~V}, \mathrm{~V}_{\mathrm{OUT}}=3.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{EN} / \mathrm{UVLO}}=1.5 \mathrm{~V}, \mathrm{RT} / \mathrm{SYNC}=191 \mathrm{k} \Omega, \mathrm{C}_{\mathrm{IN}}=1 \mu \mathrm{~F}, \mathrm{~T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}\right.$, unless otherwise noted $)$


Typical Operating Characteristics (continued)
$\left(\mathrm{V}_{\mathrm{IN}}=24 \mathrm{~V}, \mathrm{~V}_{\mathrm{GND}}=0 \mathrm{~V}, \mathrm{~V}_{\mathrm{OUT}}=3.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{EN} / \mathrm{UVLO}}=1.5 \mathrm{~V}, \mathrm{RT} / \mathrm{SYNC}=191 \mathrm{k} \Omega, \mathrm{C}_{\mathrm{IN}}=1 \mu \mathrm{~F}, \mathrm{~T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}\right.$, unless otherwise noted $)$


CONDUCTED EMI CURVE (5V OUTPUT, 25mA LOAD CURRENT)


RADIATED EMI CURVE
(5V OUTPUT, 25mA LOAD CURRENT)


## Pin Configuration

| TOP VIEW |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: |
|  | LX GND MODE RESET Vout |  |  |  |
|  |  |  |  |  |
|  |  | $1 \mathrm{~N} \square 1$ |  | $10 \square \square \mathrm{LX}$ |
|  | MAX17530 | ENJUVLO $\square 12$ | MAX17530 | 9] GND |
|  | MAX17530 | RT/SYNC $\square 3$ |  | 8 8 - MODE |
|  |  | Ss $\square 4$ |  | 7 7 - RESET |
|  |  | FB $\square 5$ |  | $6 \\|$ Vout |
|  | $\begin{array}{llll} \hline \text { IN } & \text { EN/ } & \text { RT/ } & \text { SS } \\ & \text { UVLO SYNC } \end{array}$ |  | $\mu$ MAX <br> $3 \mathrm{~mm} \times 3 \mathrm{~mm}$ |  |
|  | $\begin{gathered} \text { TDFN } \\ 3 \mathrm{~mm} \times 2 \mathrm{~mm} \end{gathered}$ |  |  |  |

## Pin Description

| PIN | NAME | FUNCTION |
| :---: | :---: | :---: |
| 1 | IN | Switching Regulator Input. Connect a X7R $1 \mu \mathrm{~F}$ ceramic capacitor from IN to GND for bypassing. |
| 2 | EN/UVLO | Active-High, Enable/Undervoltage-Detection Input. Pull EN/UVLO to GND to disable the regulator output. Connect EN/UVLO to IN for always-on operation. Connect a resistor-divider between IN, EN/UVLO, and GND to program the input voltage at which the device is enabled and turns on. |
| 3 | RT/SYNC | Oscillator Timing Resistor Input. Connect a resistor from RT/SYNC to GND to program the switching frequency from 100 kHz to 2.2 MHz . See the Switching Frequency (RT/SYNC) section for details. An external pulse can be applied to RT/SYNC through a coupling capacitor to synchronize the internal clock to the external pulse frequency. See the External Synchronization section for details. |
| 4 | SS | Soft-Start Capacitor Input. Connect a capacitor from SS to GND to set the soft-start time. Leave SS unconnected for default 5.1 ms internal soft-start. |
| 5 | FB | Output Feedback Connection. Connect FB to a resistor-divider between VOUT and GND to set the output voltage. See Adjusting the Output Voltage section for details. |
| 6 | V OUT | External Bias Input for Internal Control Circuitry. Decouple to GND with a $0.22 \mu \mathrm{~F}$ capacitor and connect to output capacitor positive terminal with a $22.1 \Omega$ resistor for applications with an output voltage from 3.3 V to 5 V . Connect to GND for output voltages $<3.3 \mathrm{~V}$ and $>5 \mathrm{~V}$. See the External Bias section for details. |
| 7 | $\overline{\text { RESET }}$ | Open-Drain Reset Output. Pull up $\overline{\text { RESET }}$ to an external power supply with an external resistor. $\overline{\text { RESET }}$ pulls low if FB voltage drops below $92 \%$ of its set value. RESET goes high-impedance 2 ms after FB voltage rises above $95 \%$ of its set value. |
| 8 | MODE | PFM/PWM Mode-Selection Input. Connect MODE to GND to enable the fixed-frequency PWM operation. Leave MODE unconnected for light-load PFM operation. |
| 9 | GND | Ground. Connect GND to the power ground plane. Connect all the circuit ground connections together at a single point. See the PCB Layout Guidelines section. |
| 10 | LX | Inductor Connection. Connect LX to the switching-side of the inductor. LX is high-impedance when the device is in shutdown. |
| - | EP | Exposed Pad (TDFN Only). Connect to the GND pin to the IC. |

## Block Diagram



# 4V to 42V, 25mA, Ultra-Small, High-Efficiency Synchronous Step-Down DC-DC Converter with $22 \mu \mathrm{~A}$ No-Load Supply Current 

## Detailed Description

The MAX17530 high-efficiency, high-voltage, synchronous step-down DC-DC converter with integrated MOSFETs operates over a 4 V to 42 V input voltage range. The converter can deliver output current up to 25 mA at output voltages of 0.8 V to $0.9 \times \mathrm{V}_{\mathrm{IN}}$. The output voltage is accurate to within $\pm 1.75 \%$ over $-40^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$. The converter consumes only $22 \mu \mathrm{~A}$ of supply current in PFM mode, while regulating the output voltage at no load.
The device uses an internally-compensated, peak-current-mode-control architecture (see the Block Diagram). On the rising-edge of the internal clock, the high-side pMOSFET turns on. An internal error-amplifier compares the feedback voltage to a fixed internal reference voltage and generates an error voltage. The error voltage is compared to a sum of the current-sense voltage and a slope-compensation voltage by a PWM comparator to set the "on-time." During the on-time of the pMOSFET, the inductor current ramps up. For the remainder of the switching period (off-time), the pMOSFET is kept off and the low-side nMOSFET turns on. During the off-time, the inductor releases the stored energy as the inductor current ramps down, providing current to the output. Under overload conditions, the cycle-by-cycle currentlimit feature limits inductor peak current by turning off the high-side pMOSFET and turning on the low-side nMOSFET.

## Mode Selection (MODE)

The device features a MODE pin for selecting either the forced-PWM or PFM modes of operation. If the MODE pin is left unconnected, the device operates in PFM mode at light loads. If the MODE pin is grounded, the device operates in a constant-frequency forced-PWM mode at all loads. The mode of operation cannot be changed on-thefly during normal operation of the device.
In PWM mode, the inductor current is allowed to go negative. PWM operation is useful in frequency-sensitive applications and provides fixed switching frequency at all loads. However, the PWM mode of operation gives lower efficiency at light loads when compared to the PFM mode of operation.
PFM mode disables negative inductor current and additionally skips pulses at light loads for high efficiency. In PFM mode, the inductor current is forced to a fixed peak of 23 mA (typ) (lPFM) every clock cycle until the output rises to $102 \%$ (typ) of the nominal voltage. Once the output reaches $102 \%$ (typ) of the nominal voltage, both
high-side and low-side FETs are turned off and the device enters hibernate operation until the load discharges the output to $101 \%$ (typ) of the nominal voltage. Most of the internal blocks are turned off in hibernate operation to save quiescent current. After the output falls below $101 \%$ (typ) of the nominal voltage, the device comes out of hibernate operation, turns on all internal blocks, and again commences the process of delivering pulses of energy to the output until it reaches $102 \%$ (typ) of the nominal output voltage. The device naturally exits PFM mode when the load current increases to a magnitude of approximately:

$$
\text { IPFM - ( } \Delta I / 2 \text { ) }
$$

where $\Delta l$ is the peak-peak ripple current in the output inductor. The part enters PFM mode again if the load current reduces to approximately ( $\Delta / / 2$ ). See the Inductor Selection section for details. The advantage of the PFM mode is higher efficiency at light loads because of lower current drawn from the supply.

## Enable Input (EN/UVLO) and Soft-Start (SS)

When EN/UVLO voltage increases above 1.25 V (typ), the device initiates a soft-start sequence. The duration of the soft-start depends on the status of the SS pin voltage at the time of power-up. If the SS pin is not connected, the device uses a fixed 5 ms internal soft-start to ramp up the internal error-amplifier reference. If a capacitor is connected from SS to GND, a $5 \mu \mathrm{~A}$ current source charges the capacitor and ramps up the SS pin voltage. The SS pin voltage is used as reference for the internal error amplifier. Such a reference ramp-up allows the output voltage to increase monotonically from zero to the final set value independent of the load current.
EN/UVLO can be used as an input voltage UVLOadjustment input. An external voltage-divider between IN and EN/UVLO to GND adjusts the input voltage at which the device turns on or turns off. See Setting the Input Undervoltage-Lockout Level section for details. If input UVLO programming is not desired, connect EN/UVLO to IN (see the Electrical Characteristics table for EN/UVLO rising and falling-threshold voltages). Driving EN/UVLO low disables both power MOSFETs, as well as other internal circuitry, and reduces IN quiescent current to below $1.2 \mu \mathrm{~A}$. The SS capacitor is discharged with an internal pulldown resistor when EN/UVLO is low. If the EN/UVLO pin is driven from an external signal source, a series resistance of minimum $1 \mathrm{k} \Omega$ is recommended to be placed between the signal source output and the EN/ UVLO pin, to reduce voltage ringing on the line.

## 4V to 42V, 25mA, Ultra-Small, High-Efficiency Synchronous Step-Down DC-DC Converter with $22 \mu \mathrm{~A}$ No-Load Supply Current

## Switching Frequency (RT/SYNC)

Switching frequency of the device can be programmed from 100 kHz to 2.2 MHz by using a resistor connected from RT/SYNC to GND. The switching frequency (fsw) is related to the resistor connected at the RT/SYNC pin ( $R_{T}$ ) by the following equation, where $R_{T}$ is in $k \Omega$ and $f s w$ is in $k H z$ :

$$
R_{T}=\frac{42000}{f_{S W}}
$$

The switching frequency in ranges of 130 kHz to 160 kHz and 230 kHz to 280 kHz are not allowed for user programming to ensure proper configuration of the internal adaptive-loop compensation scheme.

## External Synchronization

The RT/SYNC pin can be used to synchronize the device's internal oscillator to an external system clock. The external clock should be coupled to the RT/SYNC pin through a 47 pF capacitor, as shown in Figure 1. The external clock logic-high level should be higher than 3 V , logic-low level lower than 0.5 V and the duty cycle of the external clock should be in the range of $10 \%$ to $70 \%$. External-clock synchronization is allowed only in PWM mode (MODE pin connected to GND). The RT resistor should be selected to set the switching frequency $10 \%$ lower than the external clock frequency. The external clock should be applied at least $500 \mu$ s after enabling the device for proper configuration of the internal loop compensation.

## External Bias (Vout)

The device provides a VOUT pin to power the internal blocks from a low-voltage supply. When the VOUT pin voltage exceeds 3.1 V , the device draws switching and quiescent current from this pin to improve the converter's efficiency. In applications with an output voltage setting from 3.3 V to 5 V , V OUT should be decoupled to GND with


Figure 1. Synchronization to an External Clock
a ceramic capacitor and be connected to the positive terminal of the output capacitor with a resistor (R4, C1), as shown in the typical application circuits. In the absence of R 4 and C 1 , the absolute maximum rating of $\mathrm{V}_{\text {OUT }}(-0.3 \mathrm{~V})$ can be exceeded (under short-circuit conditions) due to oscillations between the ceramic output capacitor and the inductance of the short-circuit path. In general, parasitic board or wiring inductance should be minimized and the output voltage waveform under short-circuit operation should be verified to ensure that the absolute maximum rating of $\mathrm{V}_{\text {OUT }}$ is not exceeded. For applications with an output voltage setting less than 3.3 V or greater than 5 V , VOUT should be connected to GND.

## Reset Output (RESET)

The device includes an open-drain RESET output to monitor output voltage. $\overline{\mathrm{RESET}}$ should be pulled up with an external resistor to the desired external power supply. RESET goes high-impedance 2 ms after the output rises above $95 \%$ of its nominal set value and pulls low when the output voltage falls below $92 \%$ of the set nominal output voltage. RESET asserts low during the hiccup timeout period.

## Startup Into a Prebiased Output

The device supports monotonic startup into a prebiased output. When the device starts into a prebiased output, both the high-side and low-side switches are turned off so that the converter does not sink current from the output. High-side and low-side switches do not start switching until the PWM comparator commands the first PWM pulse, at which point switching commences. The output voltage is then smoothly ramped up to the target value in alignment with the internal reference. Such a feature is useful in applications where digital integrated circuits with multiple rails are powered.

## Operating Input Voltage Range

The maximum operating input voltage is determined by the minimum controllable on-time. The minimum operating input voltage is determined by the maximum duty cycle and circuit voltage drops. The minimum and maximum operating input voltages for a given output voltage should be calculated as follows:

$$
\begin{gathered}
V_{\text {INMIN }}=\frac{V_{\text {OUT }}+\left(I_{\text {OUT }} \times\left(R_{\text {DCR }}+6.0\right)\right)}{D_{\text {MAX }}}+\left(l_{\text {OUT }} \times 5.1\right) \\
V_{\text {INMAX }}=\frac{V_{\text {OUT }}}{t_{\text {ONMIN }} \times f_{\text {SW }}}
\end{gathered}
$$

where $\mathrm{V}_{\text {OUT }}$ is the steady-state output voltage, IOUT is the maximum load current, $R_{D C R}$ is the $D C$ resistance of

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the inductor, $\mathrm{f}_{\mathrm{SW}}$ is the switching frequency (max), $\mathrm{D}_{\mathrm{MAX}}$ is the maximum duty cycle (0.9), and tONMIN is the worstcase minimum controllable switch on-time (128ns)

## Overcurrent Protection, HICCUP Mode

The device implements a hiccup-type overload protection scheme to protect the inductor and internal FETs under output short-circuit conditions. When the inductor peak current exceeds 0.072 A (typ) 16 consecutive times, the part enters HICCUP mode. In this mode, the part is initially operated with hysteretic cycle-by-cycle peak-current limit that continues for a time period equal to twice the soft-start time. The part is then turned off for a fixed 51 ms hiccup timeout period. This sequence of hysteretic inductor current waveforms, followed by a hiccup timeout period, continues until the shortcircuit/overload on the output is removed. Since the inductor current is bound between two limits, inductor current runway never happens.

## Thermal-Overload Protection

Thermal-overload protection limits the total power dissipation in the IC. When the junction temperature exceeds $+160^{\circ} \mathrm{C}$, an on-chip thermal sensor shuts down the device, turns off the internal power MOSFETs, allowing it to cool down. The device turns on after the junction temperature cools by $20^{\circ} \mathrm{C}$.

## Applications Information

## Inductor Selection

A low-loss inductor having the lowest possible DC resistance that fits in the allotted dimensions should be selected. Calculate the required inductance from the equation:

$$
\mathrm{L}=\frac{37000 \times \mathrm{V}_{\mathrm{OUT}}}{\mathrm{f}_{\mathrm{SW}}}
$$

where $L$ is inductance in $\mu \mathrm{H}, \mathrm{V}_{\text {OUT }}$ is output voltage and fSW is the switching frequency in kHz . Calculate the peak-peak ripple current $(\Delta I)$ in the output inductor from the equation:

$$
\Delta \mathrm{I}=\frac{1000 \times \mathrm{V}_{\text {OUT }} \times\left(1-\frac{\mathrm{V}_{\mathrm{OUT}}}{\mathrm{~V}_{\mathrm{IN}}}\right)}{\mathrm{f}_{\mathrm{SW}} \times \mathrm{L}}
$$

where $L$ is inductance in $\mu \mathrm{H}, \mathrm{V}_{\text {OUT }}$ is output voltage, $\mathrm{V}_{\text {IN }}$ is input voltage and $\mathrm{f}_{\mathrm{SW}}$ is the switching frequency in kHz .
The saturation current rating of the inductor must exceed the maximum current-limit value (lPEAK-LIMIT). The saturation current rating should be at least 0.078A.

Once the $L$ value is known, the next step is to select the right core material. Ferrite and powdered iron are commonly-available core materials. Ferrite cores have low core losses and are preferred for high-efficiency designs. Powdered iron cores have more core losses, but are relatively less expensive than ferrite cores.

## Input Capacitor Selection

Small ceramic input capacitors are recommended for the IC. The input capacitor reduces peak current drawn from the power source and reduces noise and voltage ripple on the input caused by the switching circuitry. A minimum of $1 \mu \mathrm{~F}$, X7R-grade capacitor in a package larger than 0805 is recommended for the input capacitor of the IC to keep the input-voltage ripple under $2 \%$ of the minimum input voltage, and to meet the maximum ripple-current requirements.

## Output Capacitor Selection

Small ceramic X7R-grade output capacitors are recommended for the device. The output capacitor serves two functions: storing sufficient energy to support the output voltage under load-transient conditions and stabilizing the device's internal control loop. Usually the output capacitor is sized to support a step load of $50 \%$ of the maximum output current in the application, such that the outputvoltage deviation is less than $3 \%$. Calculate the minimum required output capacitance from the following equations

| Frequency <br> Range <br> $(\mathbf{k H z})$ | Minimum Output <br> Capacitance <br> $(\boldsymbol{\mu F})$ |
| :---: | :---: |
| 100 to 130 | $\frac{25}{\mathrm{~V}_{\text {OUT }}}$ |
| 160 to 230 | $\frac{25}{\mathrm{~V}_{\text {OUT }}}$ |
| 280 to 2200 | $\frac{15}{\mathrm{~V}_{\text {OUT }}}$ |

It should be noted that dielectric materials used in ceramic capacitors exhibit capacitance loss due to DC bias levels and should be appropriately derated to ensure the required output capacitance is obtained in the application.

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## Soft-Start Capacitor Selection

The MAX17530 offers a 5.1 ms internal soft-start when the SS pin is left unconnected. When adjustable soft-start time is required, connect a capacitor from SS to GND to program the soft-start time. The minimum soft-start time is related to the output capacitance (COUT) and the output voltage ( $\mathrm{V}_{\mathrm{OUT}}$ ) by the following equation.

$$
\mathrm{t}_{\text {SS }}>0.05 \times \text { CoUT } \times \mathrm{V}_{\text {OUT }}
$$

where $\mathrm{t}_{\mathrm{SS}}$ is in milliseconds and COUT is in $\mu \mathrm{F}$. Soft-start time ( $\mathrm{t}_{\mathrm{SS}}$ ) is related to the capacitor connected at SS (CSS) by the following equation:

$$
\mathrm{C}_{S S}=6.25 \times \mathrm{t}_{\mathrm{SS}}
$$

where $\mathrm{t}_{S S}$ is in milliseconds and $\mathrm{C}_{S S}$ is in nanofarads.

## Setting the Input Undervoltage-Lockout Level

The device offers an adjustable input undervoltagelockout level. Set the voltage at which the device turns on with a resistive voltage-divider connected from IN to GND (see Figure 2). Connect the center node of the divider to EN/UVLO.
Choose R1 to be $3.3 \mathrm{M} \Omega$ (max) and then calculate R2 as follows:

$$
\mathrm{R} 2=\frac{\mathrm{R} 1 \times 1.25}{\left(\mathrm{~V}_{\mathrm{INU}}-1.25\right)}
$$

where $\mathrm{V}_{\text {INU }}$ is the voltage at which the device is required to turn on.
If the EN/UVLO pin is driven from an external signal source, a series resistance of minimum $1 \mathrm{k} \Omega$ is recommended to be placed between the signal source output and the EN/UVLO pin to reduce voltage ringing on the line.

## Adjusting the Output Voltage

The output voltage can be programmed from 0.8 V to $0.9 \times \mathrm{V}_{\mathrm{IN}}$. Set the output voltage by connecting a resistordivider from output to FB to GND (see Figure 3). Choose R2 in the range of $25 \mathrm{k} \Omega$ to $100 \mathrm{k} \Omega$ and calculate R1 with the following equation:

$$
\mathrm{R} 1=\mathrm{R} 2 \times\left[\frac{\mathrm{V}_{\mathrm{OUT}}}{0.8}-1\right]
$$

## Transient Protection

In applications where fast line transients or oscillations with a slew rate in excess of $15 \mathrm{~V} / \mu$ s are expected during power-up or steady-state operation, the MAX17530 should be protected with a series resistor that forms a lowpass filter with the input ceramic capacitor (Figure 4).

These transients can occur in conditions such as hotplugging from a low-impedance source or due to inductive load-switching and surges on the supply lines.

## Power Dissipation

At a particular operating condition, the power losses that lead to temperature rise of the device are estimated as follows:

$$
\begin{gathered}
\text { PLOSS }^{=}\left(\text {POUT } \times\left(\frac{1}{\eta}-1\right)\right)-\left(I_{\text {OUT }}{ }^{2} \times \mathrm{R}_{\text {DCR }}\right) \\
\text { POUT }=\mathrm{V}_{\text {OUT }} \times \mathrm{I}_{\text {OUT }}
\end{gathered}
$$

where POUT is the output power, $\eta$ is the efficiency of power conversion, and $R_{D C R}$ is the $D C$ resistance of the output inductor. See the Typical Operating Characteristics section for the power-conversion efficiency, or measure the efficiency to determine the total power dissipation.


Figure 2. Adjustable EN/UVLO Network


Figure 3. Setting the Output Voltage


Figure 4. Transient Protection

The junction temperature $\left(T_{J}\right)$ of the device can be estimated at any ambient temperature ( $\mathrm{T}_{\mathrm{A}}$ ) from the following equation:

$$
T_{J}=T_{A}+\left(\theta_{J A} \times P_{\text {LOSS }}\right)
$$

where $\theta_{\mathrm{JA}}$ is the junction-to-ambient thermal impedance of the package.
Junction temperature greater than $+125^{\circ} \mathrm{C}$ degrades operating lifetimes.

## PCB Layout Guidelines

Careful PCB layout (Figure 5) is critical to achieving clean and stable operation. The switching power stage requires particular attention. Follow these guidelines for good PCB layout:

- Place the input ceramic capacitor as close as possible to $\mathrm{V}_{\mathrm{IN}}$ and GND pins
- Minimize the area formed by the LX pin and inductor connection to reduce the radiated EMI
- Ensure that all feedback connections are short and direct
- Route high-speed switching node (LX) away from the signal pins
For a sample PCB layout that ensures the first-pass success, refer to the MAX17530 evaluation kit data sheet.


Figure 5. Layout Guidelines

> 4 V to $42 \mathrm{~V}, 25 \mathrm{~mA}$, Ultra-Small, High-Efficiency Synchronous Step-Down DC-DC Converter with $22 \mu \mathrm{~A}$ No-Load Supply Current

## Typical Application Circuits



Figure 6. High-Efficiency 5V, 25mA Regulator


Figure 7. High-Efficiency 3.3V, 25mA Regulator


Figure 8. Small-Footprint 5V, 25mA Regulator

## Typical Application Circuits (continued)



Figure 9. Small-Footprint 3.3V, 25mA Regulator


Figure 10. Small-Footprint 1.8V, 25mA Regulator


Figure 11. Small-Footprint 12V, 25mA Step-Down Regulator

Ordering Information

| PART | TEMP RANGE | PIN-PACKAGE |
| :---: | :---: | :---: |
| MAX17530ATB+ | $-40^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$ | 10 TDFN-EP* |
| MAX17530AUB+ | $-40^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$ | $10 \mu \mathrm{MAX}$ |
| +Denotes a lead(Pb)-free/RoHS-compliant package. *EP = Exposed pad. |  |  |

Chip Information
PROCESS: BiCMOS

## Revision History

| REVISION <br> NUMBER | REVISION <br> DATE | DESCRIPTION | PAGES <br> CHANGED |
| :---: | :---: | :--- | :---: |
| 0 | $11 / 14$ | Initial release | - |
| 1 | $3 / 15$ | Updated Typical Application Circuits and Typical Operating Characteristics section | $1,5-8,16,17$ |
| 2 | $8 / 17$ | Updated Title to include 4V, Features and Benefits, Mode Selection (MODE), <br> Overcurrent Protection, HICCUP Mode, Setting the Input Undervoltage-Lockout <br> Level, and Power Dissipation sections. Updated the Electrical Characteristics <br> table including global characteristics and Note 3. Inserted new Note 1 to <br> Absolute Maximum Ratings, and added TOC43 and TOC44. Updated all Typical <br> Application Circuits and Block Diagram. | 1-20 |

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